3

Product Preview

128K x 8 Bit Static Random Access Memory

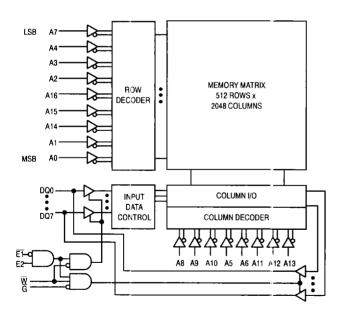
The MCM6226BA is a 1,048,576 bit static random access memory organized as 131,072 words of 8 bits, fabricated using high-performance silicon-gate CMOS technology. Static design eliminates the need for external clocks or timing strobes while CMOS circuitry reduces power consumption and provides for greater reliability.

The MCM6226BA is equipped with both chip enable ($\overline{\text{E1}}$ anc E2) and output enable ($\overline{\text{G}}$) pins, allowing for greater system flexibility and eliminating bus contention problems.

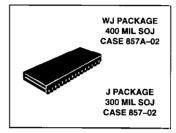
The MCM6226BA is available in 300 mil and 400 mil, 32 lead surface-mount SOJ packages.

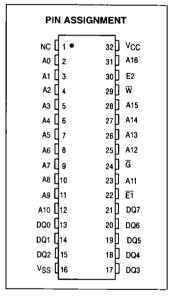
- Single 5 V ± 10% Power Supply
- Fast Access Times: 15/17/20/25/35 ns
- · Equal Address and Chip Enable Access Times
- · All Inputs and Outputs are TTL Compatible
- · Three State Outputs
- Low Power Operation: 18)/170/160/140/115 mA Maximum, Active AC

BLOCK DIAGRAM



MCM6226BA





A0 - A16 Address Inputs W Write Enable G Output Enable E1, E2 Chip Enables DQ0 - DQ7 Data Inputs/Outputs NC No Connection VCC + 5 V Power Supply VSS Ground

This document contains information on a new product under development. Motor, la reserves the right to change or discontinue this product without notice,

5/95

TRUTH TABLE

Ē1	E2	G	W	Mode	I/O Pin	Cycle	Current
Н	Х	X	Х	Not Selected	High-Z	_	SB1, SB2
X	L	X	Х	Not Selected	High-Z	_	ISB1, ISB2
L	Н	Н	Ι	Output Disabled	High-Z	_	^I CCA
L	Н	L	Н	Read	D _{c-ut}	Read	ICCA
L	Н	Х	L	Write	Dn	Write	ICCA

H = High, L = Low: X = Don't Care

ABSOLUTE MAXIMUM RATINGS (See Note)

Rating	Symbol	Value	Unit
Power Supply Voltage Relative to V _{SS}	Vcc	- 0.5 to 7.0	V
Voltage Relative to V _{SS} for Any Pin Except V _{CC}	V _{in} , V _{out}	- 0.5 to V _{CC} + 0.5	٧
Output Current (per I/O)	lout	± 20	mA
Power Dissipation	PD	1.0	w
Temperature Under Bias	T _{bias}	- 10 to + 85	°C
Operating Temperature	TA	0 to + 70	°C
Storage Temperature	T _{stg}	- 55 to + 150	°C

NOTE: Permanent device damage may occur if ABSO UTE MAXIMUM RATINGS are exceeded Functional operation should be restric ed to RECOMMENDED OPERATING CONDITIONS. Exposure to higher than recommended voltages for extended periods of time could affect device reliability.

This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields; however, it is advised that normal precautions be taken to avoid application of any voltage higher than maximum rated voltages to these high–impedance circuits.

This CMOS memory circuit has been designed to meet the dc and ac specifications shown in the tables, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow of at least 500 linear feet per minute is maintained.

DC OPERATING CONDITIONS AND CHARACTERISTICS

 $(V_{CC} = 5.0 \text{ V} \pm 10\%, T_A = 0 \text{ to } 70^{\circ}\text{C}, \text{ Unless Otherwise Noted})$

RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Min	Max	Unit
Supply Voltage (Operating Voltage Range)	Vcc	4.5	5.5	V
Input High Voltage	ViH	2.2	V _{CC} + 0.3**	٧
Input Low Voltage	V _{IL}	- 0.5*	0.8	٧

^{*} V_{IL} (min) = -0.5 V dc; V_{IL} (min) = -2.0 V ac (pulse vidth \leq 20 ns).

DC CHARACTERISTICS AND SUPPLY CURRENTS

Parameter		Symbol	Min	Max	Unit
Input Leakage Current (All Inputs, V _{in} = 0 to V _{CC})		lkg(I)		± 1	μА
Output Leakage Current ($\overline{E}^* = V_{iH}$, $V_{out} = 0$ to V_{CC})		lkg(O)	_	± 1	μА
AC Active Supp y Current (I_{Out} = 0 mA, all inputs = V_{IL} or V_{IH} , V_{IL} = 0, V_{IH} \geq 3 V, cycle time \geq t _{AVAV} min, V_{CC} = max)	MCM6226BA-15: t _{AVAV} = 15 ns MCM6226BA-17: t _{AVAV} = 17 ns MCM6226BA-20: t _{AVAV} = 20 ns MCM6226BA-25: t _{AVAV} = 25 ns MCM6226BA-35: t _{AVAV} = 35 ns	ICCA	- - - - -	18C 17C 15C 13C 12C	mA
AC Standby Current ($V_{CC} = max$, $E^* = V_{1H}$, $f = f_{max}$)	MCM6226BA-15: t _{AVAV} = 15 ns MCM6226BA-17: t _{AVAV} = 17 ns MCM6226BA-20: t _{AVAV} = 20 ns MCM6226BA-25: t _{AVAV} = 25 ns MCM6226BA-35: t _{AVAV} = 35 ns	I _{SB1}	— — — —	45 40 35 30 25	mA
CMOS Standby Current ($\overline{E}^* \ge V_{CC} - 0.2 \text{ V}, V_{in} \le V_{SS}$ or $\ge V_{CC} - 0.2 \text{ V}, V_{CC} = \text{max}, f = 0 \text{ MHz}$)	+ 0.2 V	I _{SB2}		5	mA
Output Low Voltage (I _{OL} = + 8.0 mA)		VOL		0.4	V
Output High Voltage (I _{OH} = - 4.0 mA)		VOH	2.4		V

^{*}E1 and E2 are represented by E in this data sheet. E ? is of opposite polarity to E1.

^{**} V_{1H} (max) = V_{3C} + 0.3 V dc; V_{1H} (max) = V_{CC} + 2 / ac (pulse width \leq 20 ns).

CAPACITANCE (f = 1.0 MHz, dV = 3.0 V, TA = 25°C, Periodically Sampled Rather Than 100% Tested)

	Characteristic		Symbol	Тур	Max	Unit
Input Capacitance	All Inc	outs Except Clocks and DQs E1, E2, G, and W	C _{in} C _{ck}	4 5	6 8	pF
I/O Capacitance		DQ	C _{I/O}	5	8	pF

AC OPERATING CONDITIONS AND CHARACTERISTICS

 $(V_{CC} = 5.0 \text{ V} \pm 10\%, T_{\Delta} = 0 \text{ to} \cdot 70^{\circ}\text{C}, \text{ Unless Otherwise Noted})$

Input Pulse Levels	Output Timing Measurement Reference Level 1.5 V
Input Rise/Fall Time	Output Load See Figure 1A
Input Timing Measurement Reference Level 1.5 V	

READ CYCLE TIMING (See Notes 1, 2, and 3)

		6226	6226BA-15 6226BA-17		3 <i>A</i> 17	6226BA-20 6226BA-25			3A-25	62268	3A-35		
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Unit	Notes
Read Cycle Time	t _{AVAV}	15		17	_	20	_	25	_	35	_	ns	4
Address Access Time	tavqv	_	15		17		20	_	25	_	35	ns	
Enable Access Time	tELQV		15	_	17		20		25		35	ns	5
Output Enable Access Time	†GLQV	_	6		7	_	7	_	8		8	ns	-
Output Hold from Address Change	tAXQX	5	_	5	_	5		5		5	_	ns	
Enable Low to Output Active	†ELQX	5	_	5	_	5	_	5	_	5		ns	6, 7, 8
Output Enable Low to Output Active	tGLQX	0	_	0	_	0	-	0		0		ns	6, 7, 8
Enable High to Output High-Z	tEHQZ	0	6	0	7	0	7	0	8	0	8	ns	6, 7, 8
Output Enable High to Output High–Z	tGHQZ	0	6	0	7	0	7	0	8	0	8	ns	6, 7, 8

NOTES:

- 1. W is high for read cycle.
- 2. Product sensitivities to noise require proper grounding and decoulling of power supplies as well as minimization or elimination of bus contention conditions during read and write cycles.
- 3. E1 and E2 are represented by E in this data sheet. E2 is of oppos te polarity to E1.
- 4. All timings are referenced from the last valid address to the first transitioning address.
- 5. Addresses valid prior to or coincident with E going low.
- 6. At any given voltage and temperature, teHOZ max is less than teL 2x min, and teHOZ max is less than teLOX min, both for a given device and from device to device.
- 7. Transition is measured $\pm\,500$ mV from steady–state voltage with Liad of Figure 1B.
- 8. This parameter is sampled and not 100% tested
- 9. Device is continuously selected ($\overline{E} \le V_{IL}$, $\overline{G} \le V_{IL}$).

AC TEST LOADS

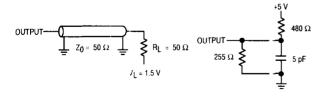


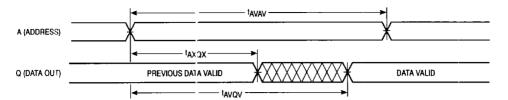
Figure 1A

Figure 1B

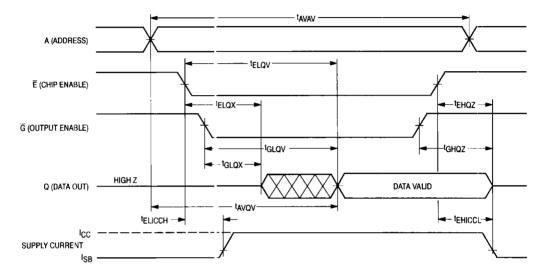
TIMING LIMITS

The table of timing values shows either a minimum or a maximum limit for each parameter. Input requirements are specified from the external system point of view. Thus, address setup time is shown as a minimum since the system must supply at least that much time (even though most devices do not require it). On the other hand, responses from the memory are specified from the device point of view. Thus, the access time is shown as a maximum since the device never provides data later than that time.

MOTOROLA FAST SRAM MCM6226BA



READ CYCLE 2 (See Notes 3 and 5)



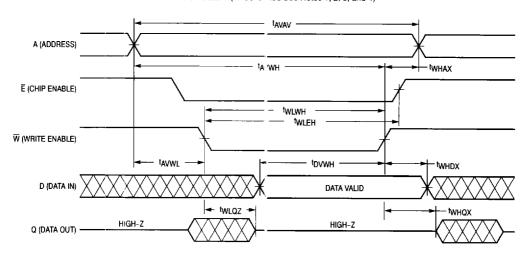
WRITE CYCLE 1 (W Controlled, See Notes 1, 2, 3, and 4)

		6226BA-15		6226BA-17		6226BA-20		6226BA-25		6226BA-35			
Parameter	Symbol	Min	Max	Unit	Notes								
Write Cycle Time	†AVAV	15		17		20	_	25	_	35	_	ns	5
Address Setup Time	†AVWL	0		0	Γ=	0	_	0	_	0		ns	
Address Valid to End of Write	tAVWH	12		14	Γ=	15	_	17		20	_	ns	
Write Pulse Width	twlwh, twleh	12	_	14	=	15	_	17	_	20	_	ns	
Data Valid to End of Write	†DVWH	7	-	8		9	_	10		11	_	ns	
Data Hold Time	twhox	0	_	0		0	_	0	_	0		ns	_
Write Low to Data High-Z	twLQZ	0	6	0	7	0	7	0	8	0	8	ns	6, 7, 8
Write High to Output Active	twhqx	5	_	5		5	_	5	_	5		ns	6, 7, 8
Write Recovery Time	twhax	0	_	0		0	_	0	_	0		ns	

NOTES:

- 1. A write occurs during the overlap of \overline{E} low and \overline{W} low.
- 2. Product sensitivities to noise require proper grounding and decour ling of power supplies as well as minimization or elimination of bus contention conditions during read and write cycles.
- 3. $\overline{\text{E1}}$ and $\overline{\text{E2}}$ are represented by $\overline{\text{E}}$ in this data sheet. $\overline{\text{E2}}$ is of opposite polarity to $\overline{\text{E1}}$.
- 4. If \overline{G} goes low coincident with or after \overline{W} goes low, the output will remain in a high-impedance state.
- 5. All timings are referenced from the last valid address to the first transitioning address.
- 6. Transition is measured ± 500 mV from steady-state voltage with k ad of Figure 1B.
- 7. This parameter is sampled and not 100% tested.
- 8. At any given voltage and temperature, tWLQZ max is less than tWHQX min both for a given device and from device to device.

WRITE CYCLE 1 (\overline{W} Controlled See Notes 1, 2, 3, and 4)



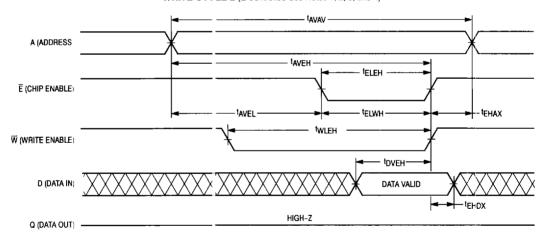
MOTOROLA FAST SRAM MCM6226BA

		6226	3A-15	-15 6226BA -17		6226BA-20		6226BA-25		6226BA-35			
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Unit	Notes
Write Cycle Time	tavav	15		17		20		25		35	-	ns	5
Address Setup Time	t _{AVEL}	0		0	_	0	-	0	-	0		ns	
Address Valid to End of Write	tAVEH	12	Γ	14	_	15	_	17	_	20	_	ns	
Enable to End of Write	tELEH, tELWH	12	Γ=	14	_	15	_	17	_	20	_	ns	6, 7
Write Pulse Width	tWLEH	12	Γ=	14	_	15	_	17		20	_	ns	
Data Valid to End of Write	tDVEH	8		9	_	9	_	10	_	11	_	ns	
Data Hold Time	^t EHDX	0	Γ=	0	_	0	-	0	_	0	_	ns	
Write Recovery Time	[†] EHAX	0		0	_	0	_	0	_	0	_	ns	

NOTES:

- 1. A write occurs during the overlap of \overline{E} low and \overline{W} low.
- 2. Product sensitivities to noise require proper grounding and decoupling of power supplies as well as minimization or elimination of bus contention conditions during read and write cycles.
- 3. $\overline{\text{E1}}$ and $\overline{\text{E2}}$ are represented by $\overline{\text{E}}$ in this data sheet $\overline{\text{E2}}$ is of opposite polarity to $\overline{\text{E1}}$.
- 4. If G goes low coincident with or after W goes low, the output will remain in a high-impedance state.
- 5. All timings are referenced from the last valid address to the first transitioning address.
- 6. If E goes low coincident with or after W goes low, the output will remain in a high–impedance state.
 7. If E goes high coincident with or before W goes high, the output will remain in a high–impedance state.

WRITE CYCLE 2 (E Controlled See Notes 1, 2, 3, and 4)



ORDERING INFORMATION (Order by Full Part Number)

Motorola Memory Prefix	CM 6226BA X		Shipping Method (R2 = Tape and Reel, Blank = Rails) Speed (15 = 15 ns. 17 = 17 ns. 20 = 20 ns. 25 = 25 ns.
rathunise —			Speed (15 = 15 115, 17 = 17 11s, 20 = 20 11s, 25 = 25 11s, 35 = 35 ns) Package (WJ = 400 mil SOJ, J = 300 mil SOJ)
Full Part Numbers — MCM6226BAJ15	MCM622I-BAJ15R2	MCM6226BAWJ15	5 MCM6226BAWJ15R2
MCM6226BAJ17	MCM6226BAJ17R2	MCM6226BAWJ17	7 MCM6226BAWJ17R2
MCM6226BAJ20	MCM6226BAJ20R2	MCM6226BAWJ20	0 MCM6226BAWJ20R2
MCM6226BA.125	MCM6226BAJ25B2	MCM6226BAW.125	5 MCM6226BAW.J25B2

MCM6226BAWJ35

MCM6226BAJ35R2

MCM6226BAJ35

MCM6226BAWJ35R2